

Material Content Data Sheet

RoHS

Sales Product Name	BTS409L1 E3062A	**Issued**	14. May 2021
MA#	MA003365856		
Package	PG-TO263-5-2	**Weight***	1496.15 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.883	0.19	0.19	1927	1927
leadframe	inorganic material	phosphorus	7723-14-0	0.237	0.02		158	
	non noble metal	iron	7439-89-6	0.790	0.05		528	
	non noble metal	copper	7440-50-8	788.527	52.72	52.79	527036	527722
wire	non noble metal	aluminium	7429-90-5	1.027	0.07	0.07	687	687
encapsulation	organic material	carbon black	1333-86-4	6.358	0.42		4250	
	inorganic material	antimonytrioxide	1309-64-4	13.295	0.89		8886	
	plastics	brominated resin	-	15.029	1.00		10045	
	plastics	epoxy resin	-	109.828	7.34		73407	
	inorganic material	silicondioxide	60676-86-0	433.531	28.98	38.63	289763	386351
leadfinish	non noble metal	tin	7440-31-5	10.339	0.69	0.69	6911	6911
plating	inorganic material	phosphorus	7723-14-0	0.008			5	
	non noble metal	nickel	7440-02-0	3.422	0.23	0.23	2287	2292
solder	non noble metal	tin	7440-31-5	0.056			37	
	noble metal	silver	7440-22-4	0.070			47	
	non noble metal	lead	7439-92-1	2.671	0.18	0.18	1785	1869
heatspreader	inorganic material	phosphorus	7723-14-0	0.032			22	
	non noble metal	iron	7439-89-6	0.108	0.01		72	
	non noble metal	copper	7440-50-8	107.943	7.21	7.22	72147	72241
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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